

January 7, 1998

TEL:805-498-2111 FAX:805-498-3804 WEB:<http://www.semtech.com>

## AXIAL LEADED HERMETICALLY SEALED FAST RECOVERY RECTIFIER DIODE

## QUICK REFERENCE DATA

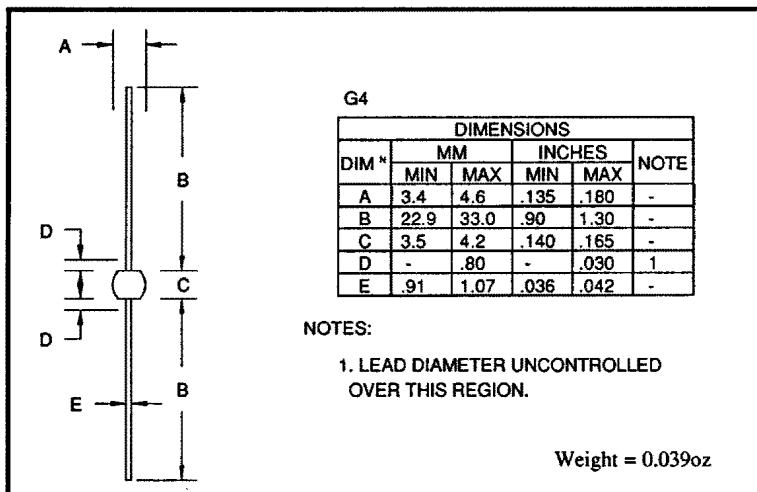
- Low reverse recovery time
- Hermetically sealed in Metoxilite fused metal oxide
- Low switching losses
- High thermal shock resistance
- Soft, non-snap off, recovery characteristics

- $V_R = 1000V$
- $I_F = 3.25A$
- $t_{rr} = 150\text{nS}$
- $I_R = 1\mu\text{A}$

## ABSOLUTE MAXIMUM RATINGS (@ 25°C unless otherwise specified)

	Symbol	3SFR0	Unit
Working reverse voltage	$V_{RWM}$	1000	V
Repetitive reverse voltage	$V_{RRM}$	1000	V
Average forward current (@ 55°C, lead length 0.375")	$I_{F(AV)}$	3.25	A
Repetitive surge current (@ 55°C in free air, lead length 0.375")	$I_{FRM}$	15.0	A
Non-repetitive surge current ( $t_p = 8.3\text{mS}$ , @ $V_R$ & $T_{jmax}$ )	$I_{FSM}$	80.0	A
Storage temperature range	$T_{STG}$	-65 to +175	°C
Operating temperature range	$T_{OP}$	-65 to +175	°C

## MECHANICAL



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**ELECTRICAL CHARACTERISTICS** (@ 25°C unless otherwise specified)

	Symbol	3SFR0	Unit
Average forward current max. (pcb mounted; TA = 55°C) for sine wave for square wave (d = 0.5)	I <sub>F(AV)</sub> I <sub>F(AV)</sub>	1.2 1.3	A A
Average forward current max. (TL = 55°C; L = 3/8") for sine wave for square wave	I <sub>F(AV)</sub> I <sub>F(AV)</sub>	3.00 3.25	A A
I <sup>2</sup> t for fusing (t = 8.3mS) max.	I <sup>2</sup> t	26	A <sup>2</sup> S
Forward voltage drop max. @ IF = 3.0A, T <sub>j</sub> = 25°C	V <sub>F</sub>	1.5	V
Reverse current max. @ VRWM, T <sub>j</sub> = 25°C @ VRWM, T <sub>j</sub> = 100°C	I <sub>R</sub> I <sub>R</sub>	1.0 25	µA µA
Reverse recovery time max. 0.5A IF to 1.0A I <sub>R</sub> . Recovers to 0.25A I <sub>RR</sub> .	t <sub>rr</sub>	150	nS
Junction capacitance typ. @ VR = 5V, f = 1MHz	C <sub>j</sub>	80	pF

**THERMAL CHARACTERISTICS**

	Symbol	3SFR0	Unit
Thermal resistance - junction to lead Lead length = 0" Lead length = 0.375"	R <sub>θJL</sub> R <sub>θJL</sub>	4 20	°C/W °C/W
Thermal resistance - junction to amb. on 0.06" thick pcb. 1 oz. copper.	R <sub>θJA</sub>	75	°C/W

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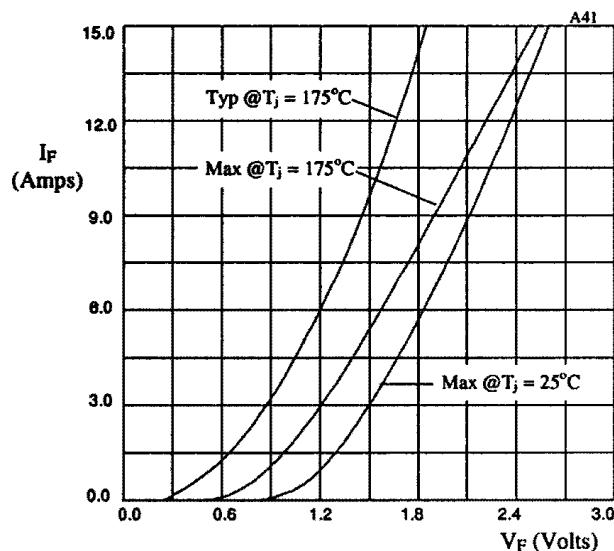


Fig 1. Forward voltage drop as a function of forward current.

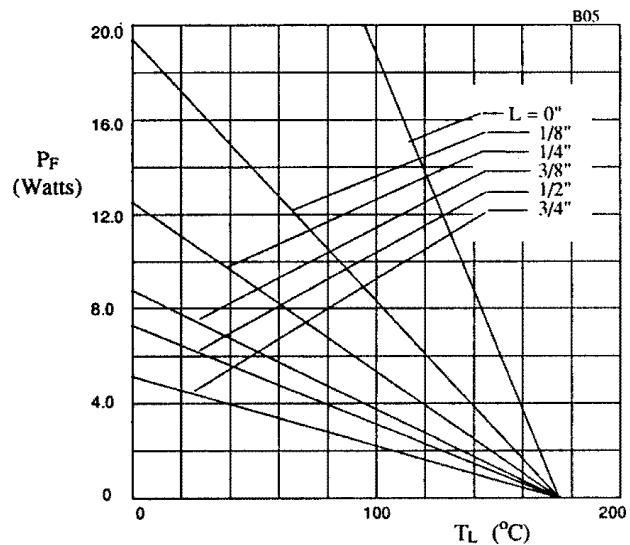


Fig 2. Maximum power versus lead temperature.

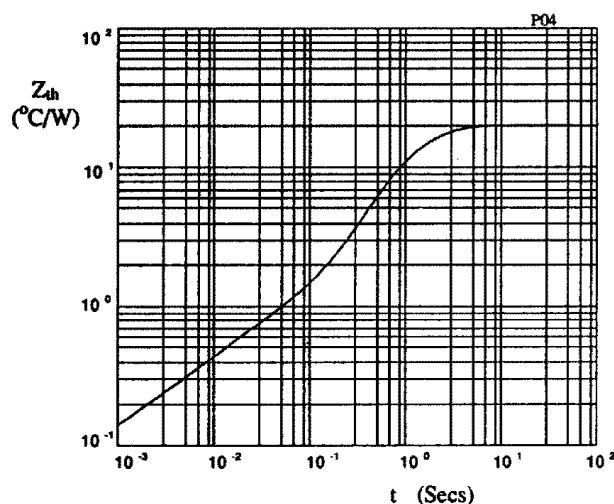


Fig 3. Transient thermal impedance characteristic.

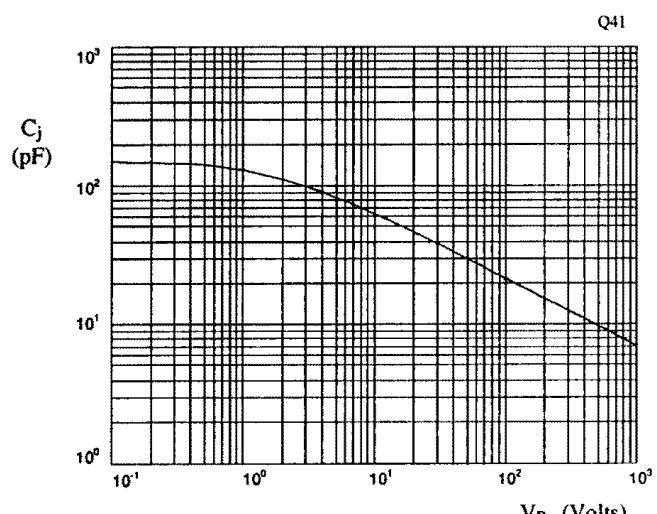


Fig 4. Typical junction capacitance as a function of reverse voltage.

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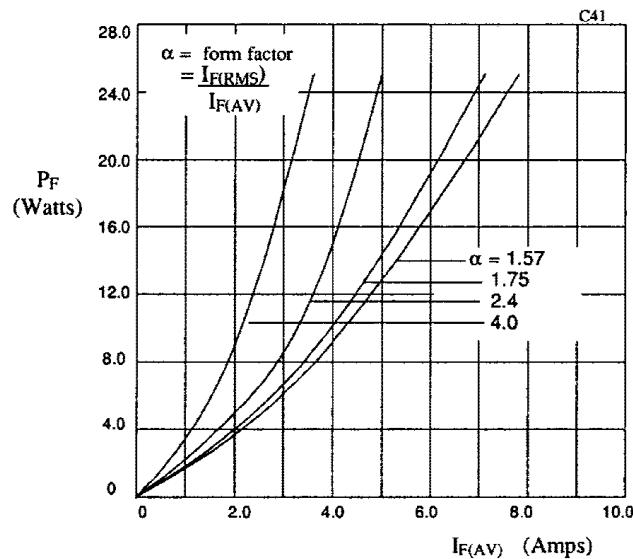


Fig 5. Forward power dissipation as a function of forward current, for sinusoidal operation.

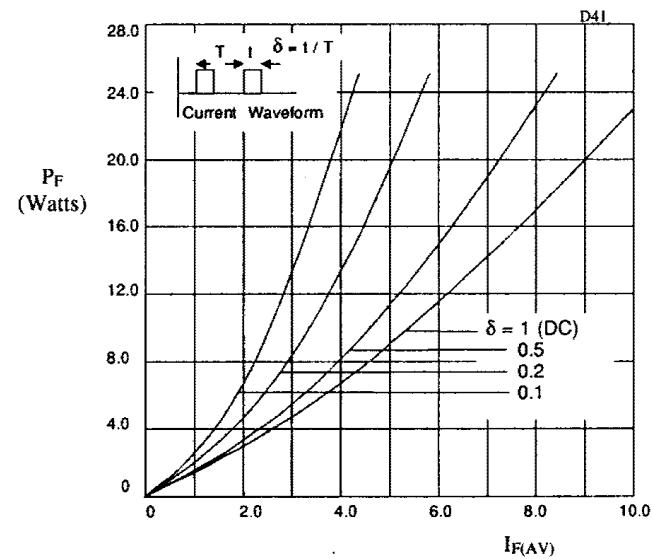


Fig 6. Forward power dissipation as a function of forward current, for square wave operation.

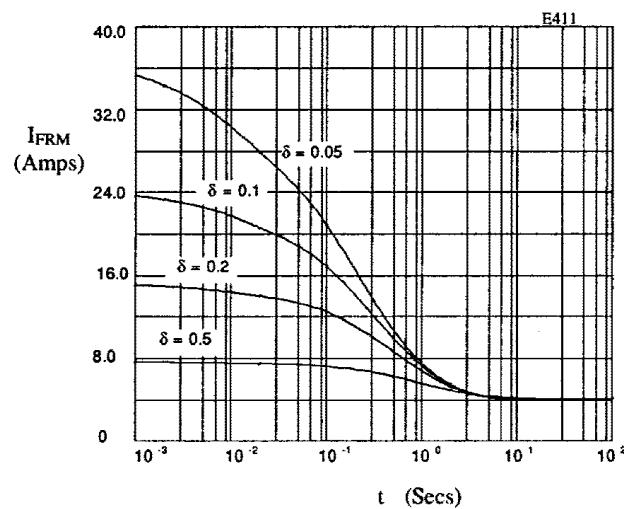


Fig 7. Typical repetitive forward current as a function of pulse width at 55°C;  $R_{\theta JL} = 20$  °C/W;  $V_{RWM}$  during  $1 - \delta$ .

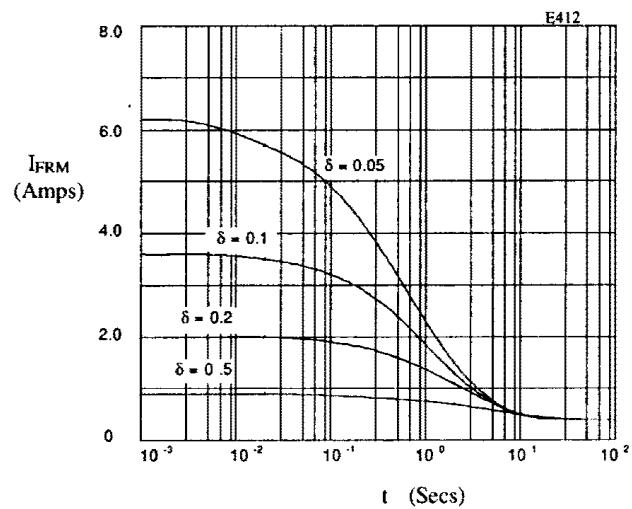


Fig 8. Typical repetitive forward current as a function of pulse width at 100°C;  $R_{\theta JL} = 80$  °C/W;  $V_{RWM}$  during  $1 - \delta$ .